

MGV High Current Molded SMT Power Inductors MGV0302 Series

FEATURES AND APPLICATIONS

Laird MGV series high current power inductors improve performance, reliability and power efficiency. A lower profile benefits consumer electronics and telecom design. Products feature extremely low DCR with greater efficiency and enable a large current in a small size. Inductors are of magnetic shielding and molded construction and perform in operating temperatures ranging from -40 C to 125 C including self-heating rise in temperature.

FEATURES

- Magnetic shielded structure
- Low DCR and high efficiency
- Low profile and miniaturization
- High reliability

APPLICATIONS

- DC-DC Converter and Power Suppliers
- LCD TV'S and Gaming Console
- Tablet, Notebooks, Servers and Printers
- Networking and Data storage
- GPS, Set-top-box and Base stations
- Smart meters and Medical instruments



PART NUMBER EXPLANATION

MGV 0302 4R7 M - 10

Product series code	Product size code	Inductance value code (i.e. 4R7: 4.7 μ H)	Tolerance % (i.e. M: \pm 20%)	Standard Catalog P.N
MGV	0302	4R7	M	10

Note: Automotive grade parts are also available, a specific P.N will be assigned upon request. Please contact laird local sales for details.

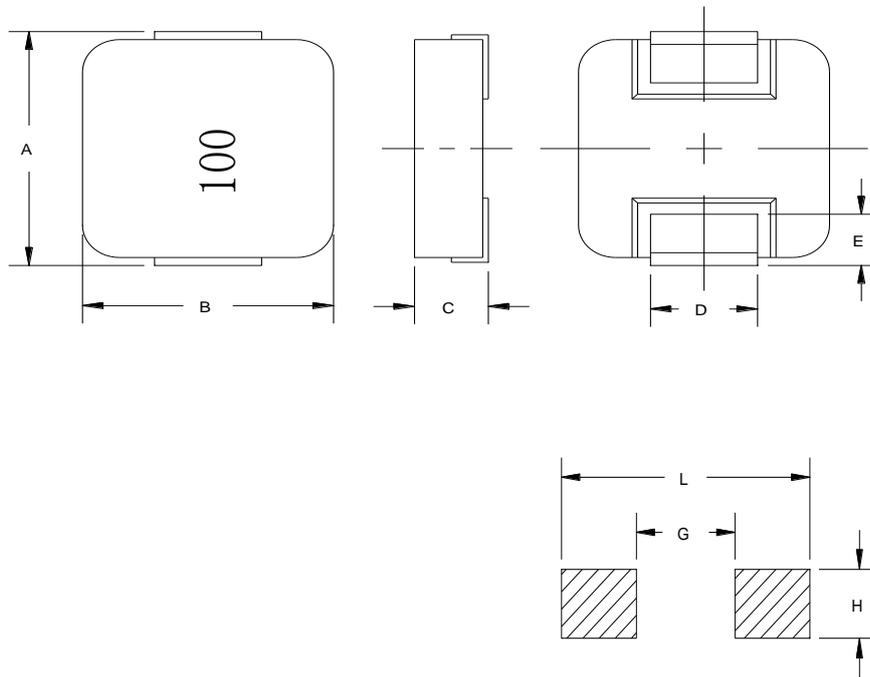
ELECTRICAL SPECIFICATIONS

- Tolerance: M: \pm 20% or N: \pm 30%
- Inductance tested at 100KHz, 1.0V
- Heat Rated Current (Irms) is defined based on temperature rise approximate 40°C without core loss (ambient temperature 25 \pm 5°C)
- Saturation Current (Isat) is the DC current at which the inductance drops off approximately 30% from its value without current. (ambient temperature 25 \pm 5°C)
- Operating temperature range: -40°C~+125°C (including self-heating temperature rise)
- Storage temperature range (packaging conditions): -10°C~+40°C and RH 60%(MAX.)

Note: Heat Rated Current (Irms) is tested on a typical PCB and apply a constant current in still air. The temperature rise is dependent on the application system condition including PCB PAD pattern, trace width and thickness and adjacent components etc. It's suggested to verify the temperature rise of the component under the real operation application conditions.

SPECIFICATION FOR APPROVAL

1.MECHANICAL & DIMENSIONS



(UNIT: mm)

A	3.50±0.20
B	3.20±0.20
C	1.80±0.20
D	1.20±0.20
E	0.70±0.20
L	4.10 ref
G	1.90 ref
H	1.45 ref

REMARK

2.PART NUMBER NOMENCLATOR:

MGV 0302 100 M - 1X

A B C D E

A: Product Series.

B: Series number, part size

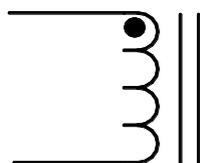
C: Inductance code

D: Inductance Tolerance. (M=±20% ,N=±30%)

E: "X"=0:Standard catalog part number

"X"=1-9:Controlled customized part **or** different performance than std catalog part. And "5-9" is for automotive grade.

3.EQUIVALENT CIRCUIT:



SPECIFICATION FOR APPROVAL

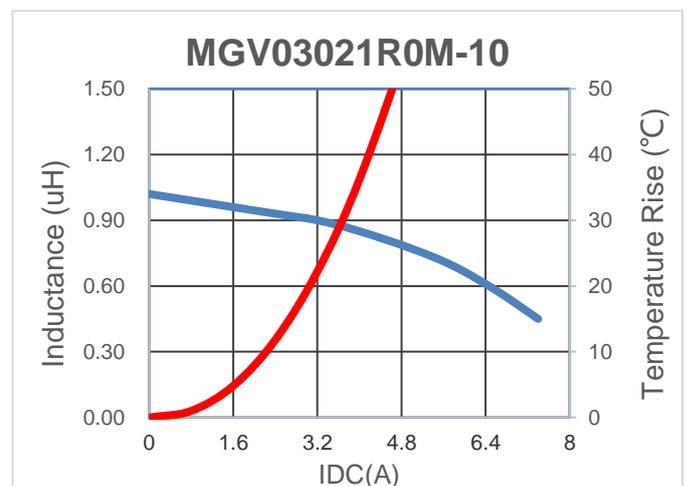
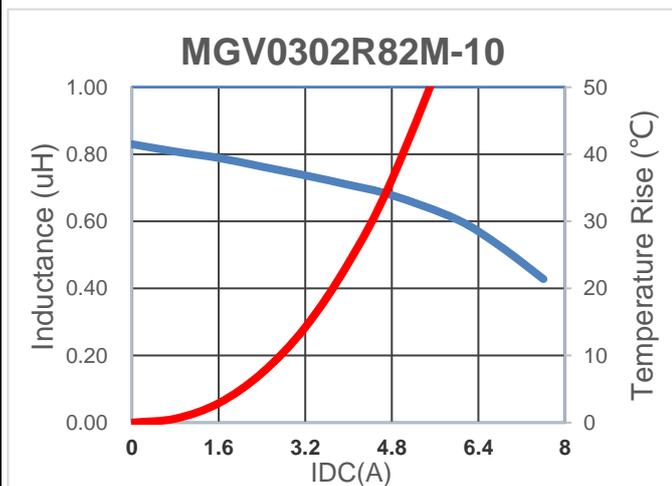
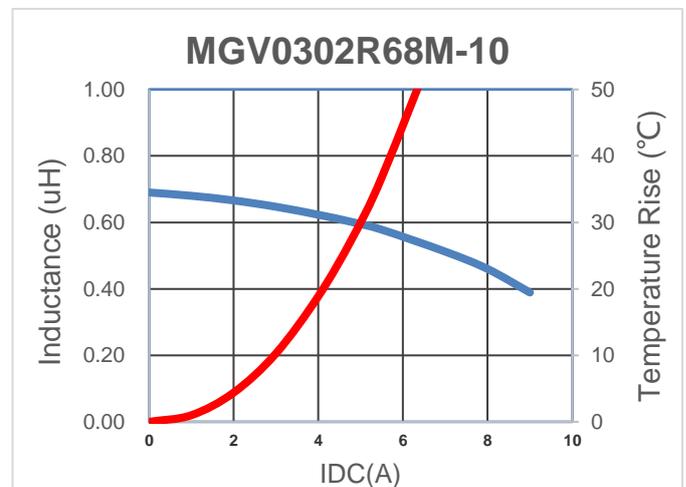
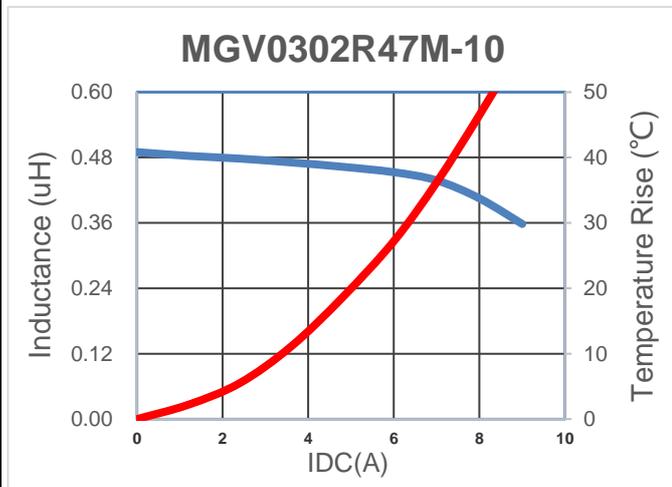
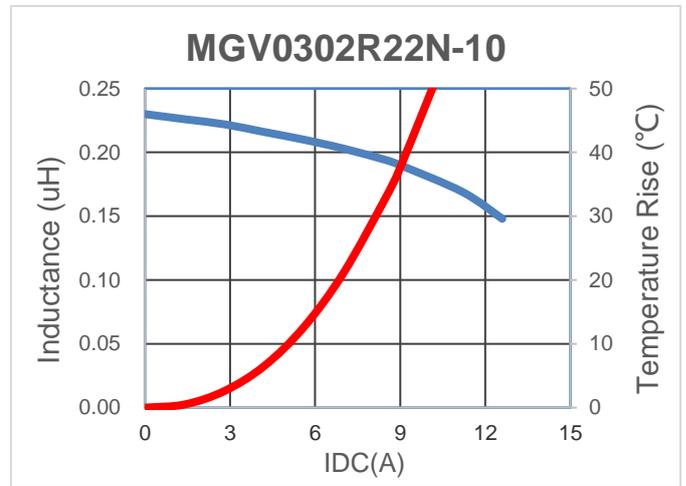
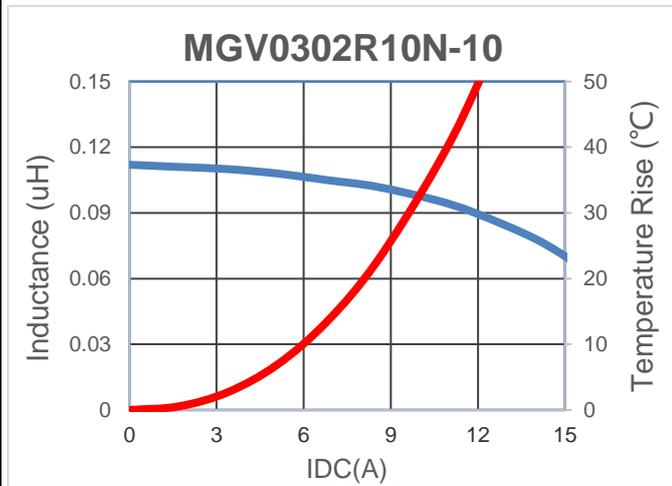
PART NUMBER	INDUCTANCE (uH)	I _{rms} (A) Typ.	I _{sat} (A) Typ.	DCR(mΩ) Typ	DCR(mΩ) Max	REMARK
MGV0302R10N-10	0.10±30%	10.5	14.0	6.6	9.0	
MGV0302R22N-10	0.22±30%	9.0	11.2	11.0	14.0	
MGV0302R47M-10	0.47±20%	7.0	9.0	19.7	23.0	
MGV0302R68M-10	0.68±20%	5.5	7.0	25.5	29.0	
MGV0302R82M-10	0.82±20%	4.8	6.0	27.0	32.0	
MGV03021R0M-10	1.00±20%	4.0	5.0	32.0	38.0	
MGV03021R2M-10	1.20±20%	3.9	4.5	39.0	47.0	
MGV03021R5M-10	1.50±20%	3.8	4.0	42.0	50.0	
MGV03022R2M-10	2.20±20%	3.5	3.7	65.0	75.0	
MGV03023R3M-10	3.30±20%	3.0	3.5	125	145	
MGV03024R7M-10	4.70±20%	2.6	3.0	172	200	
MGV03026R8M-10	6.80±20%	1.9	2.2	260	300	
MGV0302100M-10	10.0±20%	1.4	1.6	366	422	

GENERAL SPECIFICATION:

- 1, Test conditions(L): 100KHz, 1Vrms
- 2, Operating temperature: -55°C to +125°C (Including self-heating)
- 3, Storage temperature: -10°C to +40°C
- 4, Humidity range: 60% RH Max.
- 5, Heat Rated Current (I_{rms}) will cause the coil temperature rise approximately Δt of 40°C
- 6, Saturation Current (I_{sat}) will cause L0 to drop approximately 30%.
- 7, Part Temperature (Ambient+Temp. Rise) : Should not exceed 125°C under worst case operating condi
- 8, Storage condition (component in its packaging)

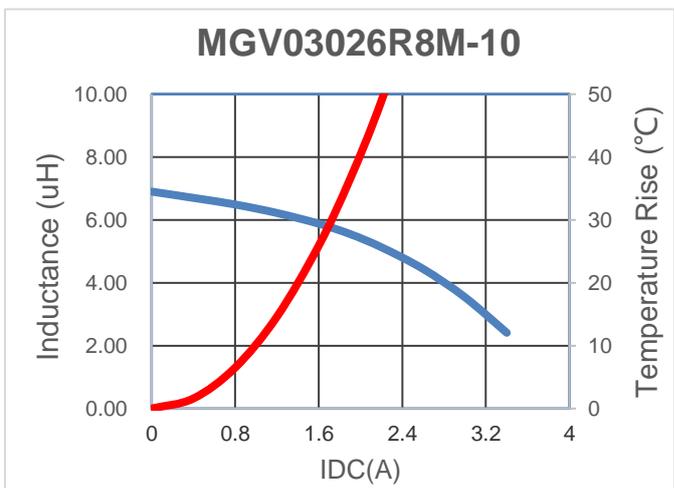
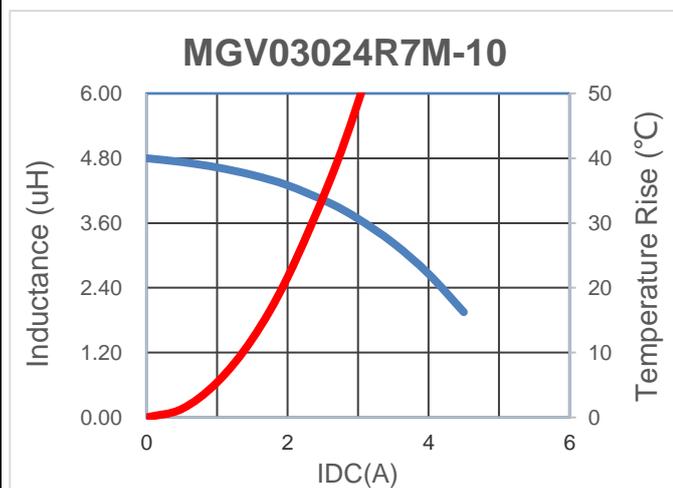
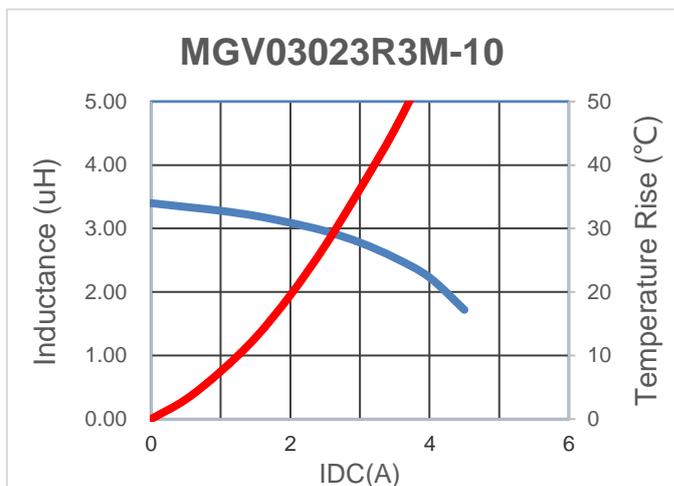
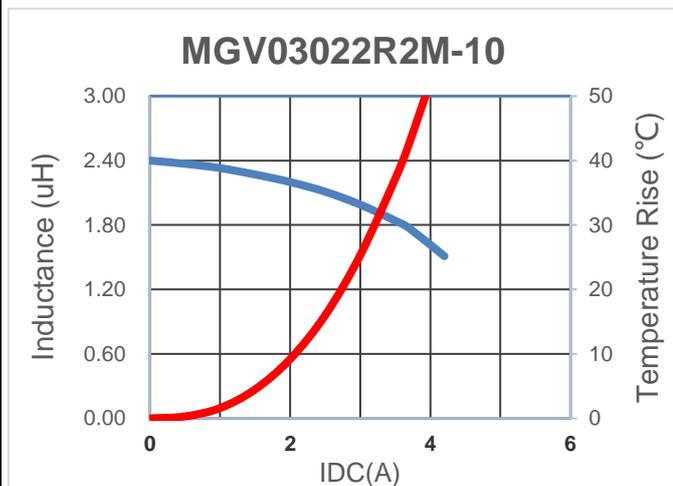
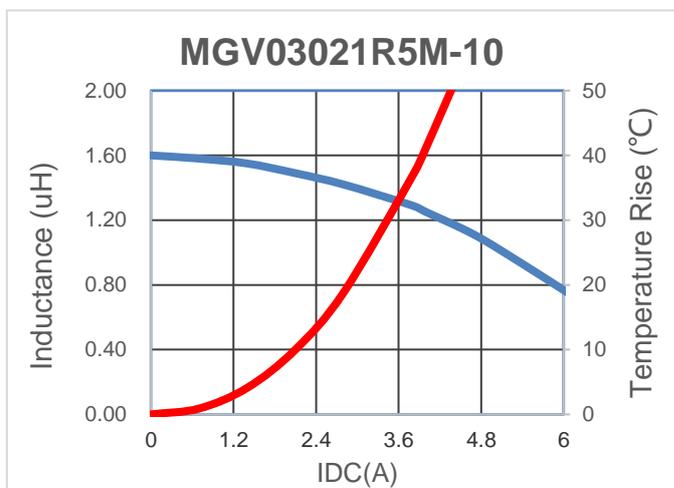
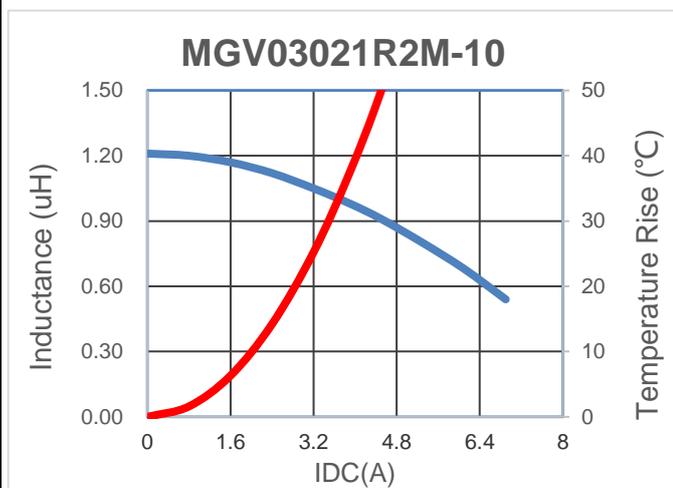
SPECIFICATION FOR APPROVAL

Characteristics Curve



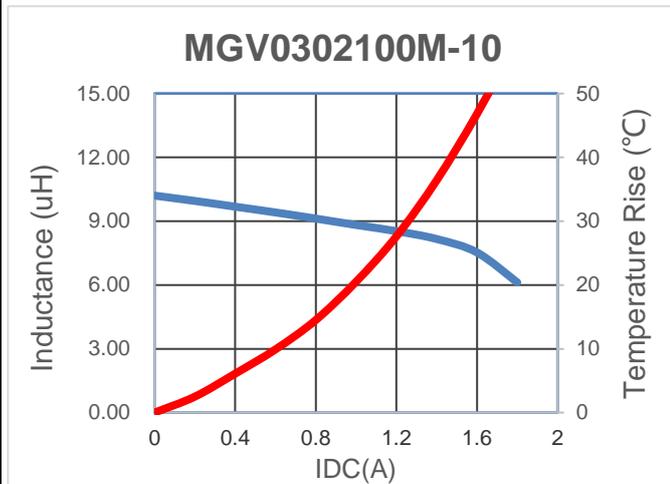
SPECIFICATION FOR APPROVAL

Characteristics Curve



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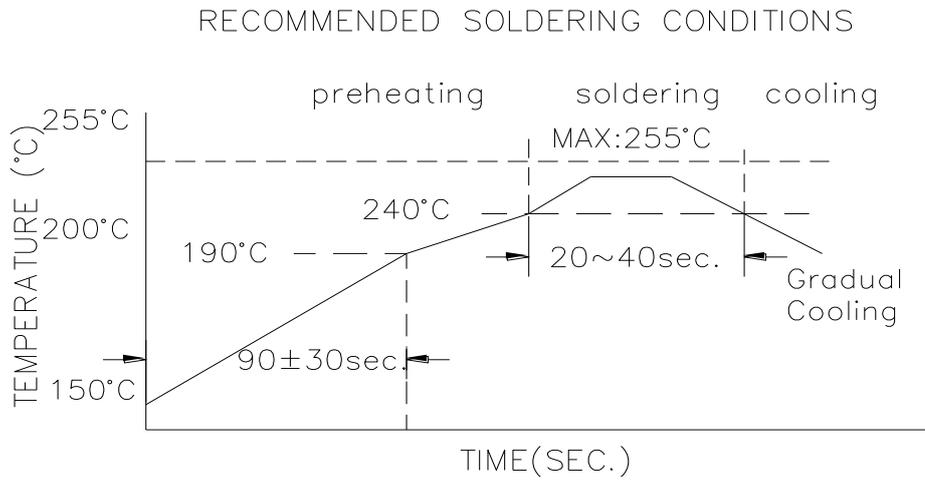
Characteristics Curve



Recommended Soldering Conditions

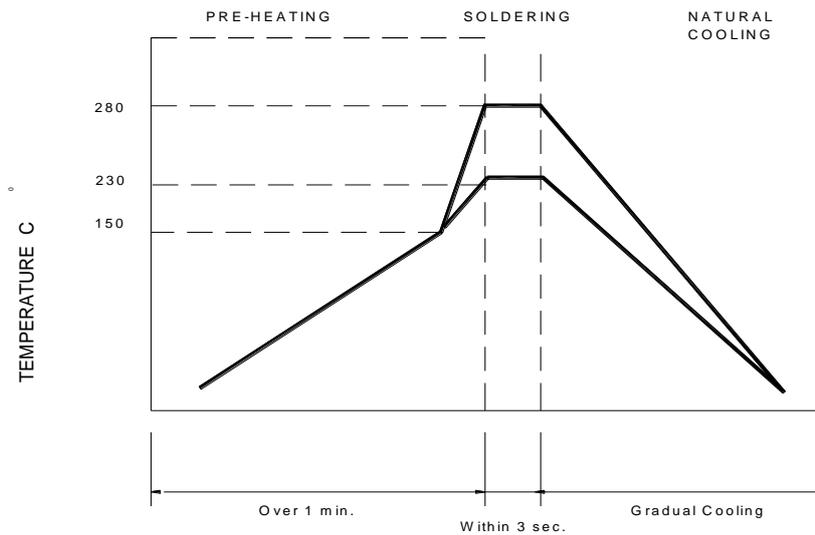
For Lead-Free Application

Figure 1 . Re-flow Soldering



Reflow times: 3 times max

Figure 2 . Hand Soldering



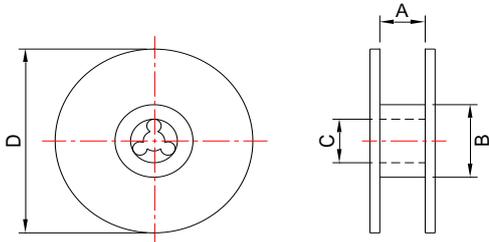
Hand solder times: 1 time max

Reliability and Testing Conditions / Pin Type Power Inductors

SMD series(Consumer)		
Item	Reference	Additional Requirements
Operating temperature range	-55°C ~ +125°C (Including self-temperature rise)	
Storage temperature and humidity range	-10°C to +40°C , 60% RH Max	
High Temperature Exposure (Storage)	MIL-STD-202 Method 108	85±2°C, 168+24hours
Temperature Cycling	JESD22 Method JA-104	-40°C → +85, transforming interval:20s, 100cycles
Operational Life	MIL-PRF-2	85±°C, 168+24hours Apply maximum rated voltage and current according part drawing
External Visual	MIL-STD-883 Method 2009	Inspect device construction, marking and workmanship. Electrical Test not required.
Physical Dimension	JESD22 Method JB-100	Verify physical dimensions to the applicable device detail specification. Note: User(s) and Suppliers spec. Electrical Test not required
Vibration	MIL-STD-202 Method 204	10~55Hz, 1.5mm, 2 hours in each 3 mutually perpendicular directions (total of 6 hours)
Resistance to Soldering Heat	MIL-STD-202 Method 210	1. Max. 260±5°C, 10±1s, 2 times 2. Solder Composition: Sn/3Ag/0.5Cu
Solderability	J-STD-002	245±5°C, 5±1sec, Solder: Sn/3.0Ag/0.5Cu
Electrical Characterization	Print Spec	Parametrically test per lot and sample size requirements, summary to show Min, Max, Mean and Standard deviation at room as well as Min and Max Operating temperatures
Board Flex	AEC-Q200-005	2mm, 30±1s
Terminal Strength(SMD)	AEC-Q200-006	10N, 5S, X,Y direct

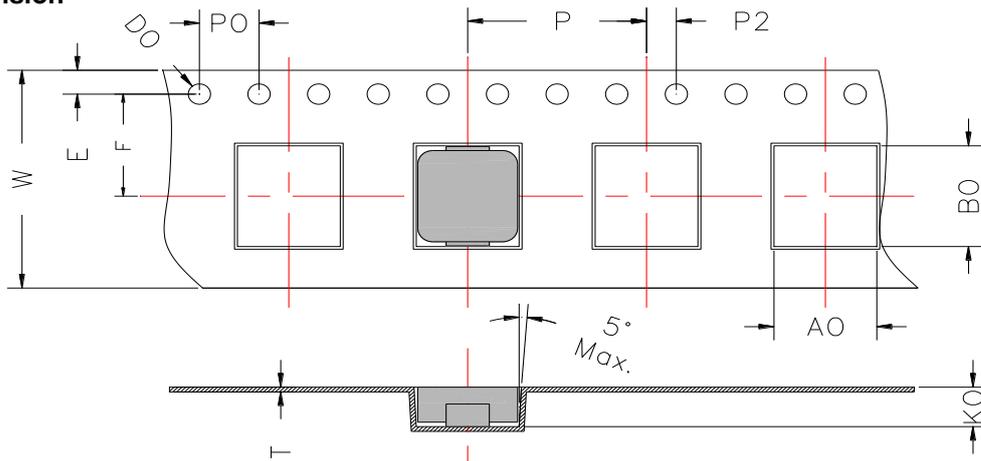
PACKAGING

Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13'x12	12.4+2/-0	100 ± 2	13+0.5/-0.2	330

Tape Dimension

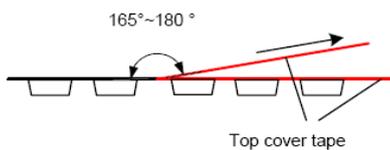


W	E	F	P	A0	B0	P2	P0	K0	t	D0
12.0±0.3	1.75±0.1	5.5±0.1	8±0.1	3.5±0.1	3.8±0.1	2.0±0.1	4.0±0.1	2.3±0.1	0.35±0.05	1.5Ref.

Packaging Quantity

P/N	Chip/Reel	Inner Box	Outer Box
MGV0302 Series	3000pcs	6000pcs	12000pcs
Size	-	-	-

Peeling Off Force



The force peeling off cover tape is 10 to 100 grams			
in the arrow direction under the following conditions			
Room Temp (°C)	Room Humidity	Room atn (hPa)	Teaming Speed
5~35	45~85	860~1060	300

※Storage Conditions

1. Temperature and humidity conditions: -10-+40°C and 60% RH.
2. Recommended products should be used within 12 mont from the time of manufacturing.
3. The packaging material should be kept where no chlorin or sulfur exists in the air.
4. Allowable stacking condition of Packaqing box: max height 1.5m or 5 boxes stacking